



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B99I*FC60BBQ	A	1054	2017-07-13
Amount	UoM	Unit type	ST ECOPACK Grade	
260.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1	64	gull wing	

Comment	PACKAGE : TQFP 64 10X10X1.0 ExPad Down. MD valid for SPC582B60E1MH00Y, SPC58B54E1CG00X, SPC582B54E1BD00X, SPC582B50E1CG00X, SPC582B50E1AD00X			
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QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.80	Leadframe metal	3077

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B991*FC60BBQ						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	21.004	mg	supplier	die	Silicon (Si)	7440-21-3		20.639	mg	982622	79381	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.043	mg	2047	165	
				supplier	metallization	Copper (Cu)	7440-50-8		0.136	mg	6476	523	
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	1047	85	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	190	15	
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	48	4	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.159	mg	7570	612	
Leadframe	Copper & its alloys	85.442	mg	supplier	alloy	Copper (Cu)	7440-50-8		82.414	mg	964549	316977	
				supplier	alloy	Iron (Fe)	7439-89-6		1.938	mg	22682	7454	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.117	mg	1369	450	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.102	mg	1194	392	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.800	mg	9363	3077	
				supplier	metallization	Palladium (Pd)	7440-05-3		0.051	mg	597	196	
				supplier	metallization	Gold (Au)	7440-57-5		0.021	mg	246	81	
Die attach	Other Organic Materials	2.950	mg	supplier	glue	Silver (Ag)	7440-22-4		2.640	mg	894915	10154	
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.221	mg	74916	845	
				supplier	glue	Bismaleimide resin	Proprietary		0.089	mg	30169	342	
Bonding wire	Other inorganic materials	0.725	mg	supplier	wire	Copper (Cu)	7440-50-8		0.725	mg	1000000	2788	
Encapsulation	Other Organic Materials	149.879	mg	supplier	mold compound	Silica, vitreous	60676-86-0		129.495	mg	863997	498058	
				supplier	mold compound	Epoxy Resin	25068-38-6		11.240	mg	75001	43235	
				supplier	mold compound	Phenol Resin	29690-82-2		7.494	mg	50000	28823	
				supplier	mold compound	3-Mercaptopropyl trimeth	4420-74-0		0.749	mg	4998	2881	
				supplier	mold compound	Quartz	14808-60-7		0.450	mg	3002	1731	
				supplier	mold compound	Carbon black	1333-86-4		0.450	mg	3002	1731	